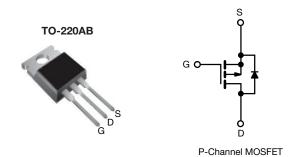
Vishay Siliconix

# **Power MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	-100				
$R_{DS(on)}(\Omega)$	V <sub>GS</sub> = -10 V 0.30				
Q <sub>g</sub> max. (nC)	38				
Q <sub>gs</sub> (nC)	6.8				
Q <sub>gd</sub> (nC)	21				
Configuration	Single				



#### **FEATURES**

- Dynamic dV/dt rating
- Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- Fast switching
- · Ease of paralleling
- Simple drive requirements
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

#### Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

#### **DESCRIPTION**

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF9530PbF		
Lead (FD)-IIee	SiHF9530-E3		
SnPb	IRF9530		
SIFU	SiHF9530		

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V <sub>DS</sub>	-100	V	
Gate-Source Voltage		$V_{GS}$	± 20	7 v
Continuous Drain Current	$V_{GS}$ at - 10 V $T_{C} = 25 ^{\circ}C$ $T_{C} = 100 ^{\circ}C$	I <sub>D</sub>	- 12	А
Continuous Drain Current	$V_{GS}$ at - 10 V $T_{C} = 100 ^{\circ}\text{C}$		-8.2	
Pulsed Drain Current <sup>a</sup>	I <sub>DM</sub>	-48	1	
Linear Derating Factor		0.59	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>	E <sub>AS</sub>	400	mJ	
Repetitive Avalanche Current <sup>a</sup>	I <sub>AR</sub>	-12	А	
Repetitive Avalanche Energy <sup>a</sup>	E <sub>AR</sub>	8.8	mJ	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	88	W
Peak Diode Recovery dV/dt <sup>c</sup>	dV/dt	- 5.5	V/ns	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering Recommendations (Peak temperature) <sup>d</sup>		300		
Mounting Torque	6-32 or M3 screw		10	lbf ⋅ in
Mounting Torque	0-32 OF IVIS SCIEW		1.1	N⋅m

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b.  $V_{DD}=$  -25 V, starting  $T_J=$  25 °C, L= 4.2 mH,  $R_g=$  25  $\Omega$ ,  $I_{AS}=$  -12 A (see fig. 12). c.  $I_{SD}\leq$  -12 A,  $dI/dt\leq$  140 A/ $\mu$ s,  $V_{DD}\leq$   $V_{DS}$ ,  $T_J\leq$  175 °C.
- d. 1.6 mm from case.



# Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	62		
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.50	-	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	1.7		

PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static						•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$		-100	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I <sub>D</sub> = -1 mA	-	-0.10	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = \	/ <sub>GS</sub> , I <sub>D</sub> = -250 μA	-2.0	-	-4.0	V
Gate-Source Leakage	I <sub>GSS</sub>	V	<sub>GS</sub> = ± 20 V	-	-	± 100	nA
-	_	V <sub>DS</sub> = -100 V, V <sub>GS</sub> = 0 V		-	-	-100	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = -80 \text{ V},$	V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C	-	-	-500	μA
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -7.2 A <sup>b</sup>	-	-	0.30	Ω
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> = -	50 V, I <sub>D</sub> = -7.2 A <sup>b</sup>	3.7	-	-	S
Dynamic					ı		ı
Input Capacitance	C <sub>iss</sub>		V 0V		860	-	
Output Capacitance	C <sub>oss</sub>	V	$V_{GS} = 0 \text{ V},$ $DS = -25 \text{ V},$	-	340	-	рF
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0	MHz, see fig. 5	ı	93	-	
Total Gate Charge	Qg		$V_{GS} = -10 \text{ V}$ $I_D = -12 \text{ A}, V_{DS} = -80 \text{ V},$ see fig. 6 and 13 b		-	38	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>GS</sub> = -10 V			-	6.8	
Gate-Drain Charge	Q <sub>gd</sub>				-	21	
Turn-On Delay Time	t <sub>d(on)</sub>				12	-	- ns
Rise Time	t <sub>r</sub>	$V_{DD} = -50 \text{ V, } I_D = -12 \text{ A,}$ $R_g = 12 \ \Omega, R_D = 3.9 \ \Omega, \text{ see fig. 10}^{\text{ b}}$		-	52	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	31	-	
Fall Time	t <sub>f</sub>			-	39	-	
Internal Drain Inductance	L <sub>D</sub>	, ,	Between lead, 6 mm (0.25") from package and center of die contact		4.5	-	- nH
Internal Source Inductance	L <sub>S</sub>				7.5	-	
Gate Input Resistance	$R_g$	f = 1 MHz, open drain		0.4	-	3.3	Ω
<b>Drain-Source Body Diode Characteristic</b>	s	_				1	
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p -n junction diode		ı	-	-12	A
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	-	-48	
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25  ^{\circ}\text{C},  I_S = -12  \text{A},  V_{GS} = 0  \text{V}^{ \text{b}}$		-	-	-6.3	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = -12 \text{ A}, dI/dt = 100 \text{ A/µs b}$		-	120	240	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			-	0.46	0.92	μC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turi	n-on time is negligible (turn	-on is dor	minated b	y L <sub>S</sub> and	$L_D$ )

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq$  300  $\mu$ s; duty cycle  $\leq$  2 %.



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

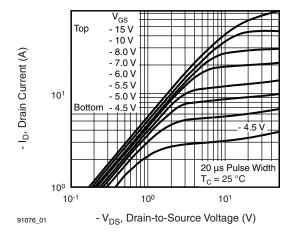


Fig. 1 -Typical Output Characteristics, T<sub>C</sub> = 25 °C

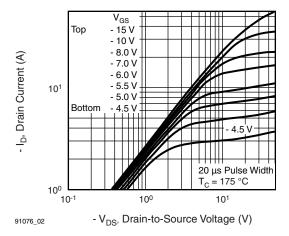


Fig. 2 - Typical Output Characteristics,  $T_C = 175$  °C

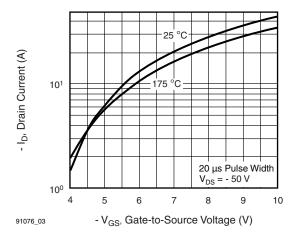


Fig. 3 - Typical Transfer Characteristics

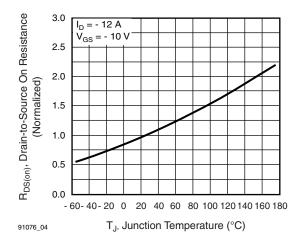


Fig. 4 -Normalized On-Resistance vs. Temperature

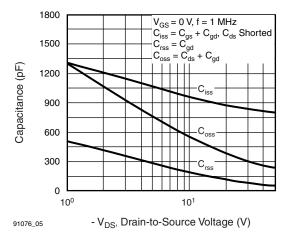


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

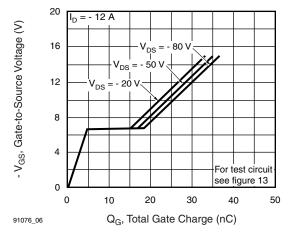


Fig. 6 -Typical Gate Charge vs. Gate-to-Source Voltage



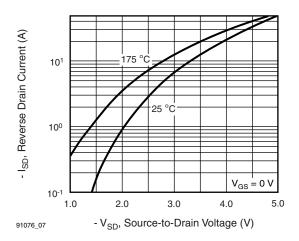


Fig. 7 - Typical Source-Drain Diode Forward Voltage

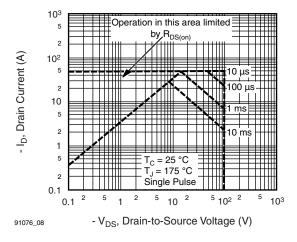


Fig. 8 - Maximum Safe Operating Area

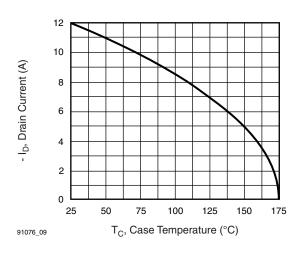


Fig. 9 - Maximum Drain Current vs. Case Temperature

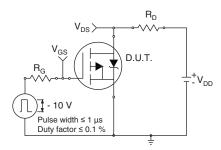


Fig. 10a - Switching Time Test Circuit

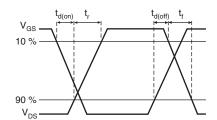


Fig. 10b - Switching Time Waveforms

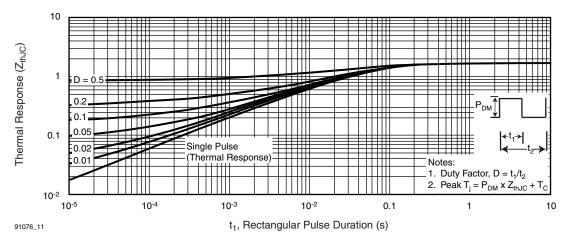


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



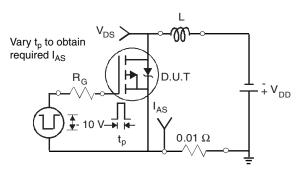


Fig. 12a - Unclamped Inductive Test Circuit

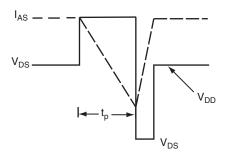


Fig. 12b - Unclamped Inductive Waveforms

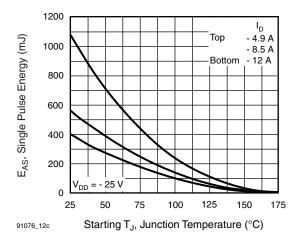


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

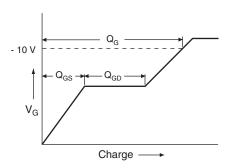


Fig. 13a - Basic Gate Charge Waveform

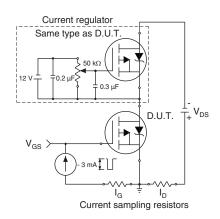
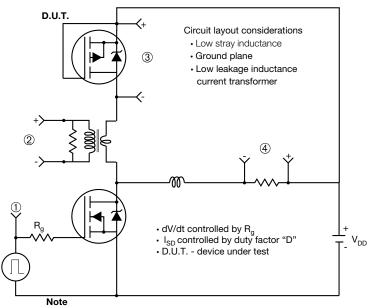


Fig. 13b - Gate Charge Test Circuit



### Peak Diode Recovery dV/dt Test Circuit



· Compliment N-Channel of D.U.T. for driver

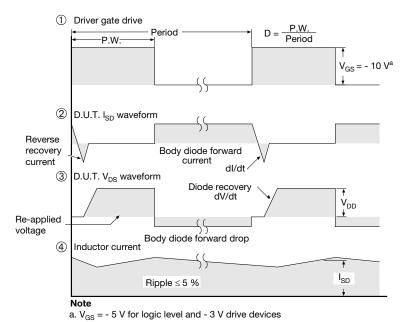


Fig. 14 -For P-Channel

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# TO-220-1



DIM	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

### Note

 $\bullet$   $M^{\star}=0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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